

**LINEAR TECHNOLOGY MATERIALS DECLARATION**

1t1724cs#pbf

(Engineering Calculation)

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**TOTAL MASS (g) : 0.132288**

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.001676	1000000	12669.2851562		
Die Coat	Dow Corning	Silicone	69430-27-9	0.000000	0	0		
Lead Frame	A42	Copper (Cu)	7440-50-8	0.000000	0	0		
		Iron (Fe)	7439-89-6	0.025972	580000	196328.5625		
		Phosphorus (P)	7723-14-0	0.000000	0	0		
		Zinc (Zn)	7440-66-6	0.000000	0	0		
		Nickel (Ni)	7440-02-0	0.018808	420000	142174.171875		
		Silicon (Si)	7440-21-3	0.000000	0	0		
		Magnesium (Mg)	7439-95-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
<b>Lead Frame Total:</b>				<b>0.044780</b>	<b>1000000</b>	<b>338502.75</b>		
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0		
		Exter. Plating Sn	7440-31-5	0.002585	1000000	19543.9414062		
		<b>External Plating Total:</b>				<b>0.002585</b>	<b>1000000</b>	<b>19543.9414062</b>
		Inter. Plating Ni	7440-02-0	0.000000	0	0		
		Inter. Plating Ag	7440-22-4	0.000358	1000000	2706.20751953		
<b>Internal Plating Total:</b>				<b>0.000358</b>	<b>1000000</b>	<b>2706.20751953</b>		
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.000611	750000	4618.6953125		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000000	0	0		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000000	0	0		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000204	250000	1542.08483887		
<b>Die Attach Total:</b>				<b>0.000815</b>	<b>1000000</b>	<b>6160.77978516</b>		
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.010624	130000	80309.359375		
		Bromine (Br)	40039-93-8	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.067828	830000	512728.09375		
		Antimony Trioxide (Sb2O3)	1309-64-4	0.000000	0	0		
		Metal Hydroxide		0.002860	35000	21619.4238281		
		Carbon Black (C)	1333-86-4	0.000409	5000	3091.72900391		
		<b>Encapsulation Total:</b>				<b>0.081721</b>	<b>1000000</b>	<b>617748.625</b>
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.000353	1000000	2668.41162109		
					<b>TOTAL MASS (g) :</b>	<b>0.132288</b>		